

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.85558	100.0	1
			Subtotal	0.85558	100	1
Wire	Impurity	Non hazardous		0.00002	0.01	0.00002
	Pure metal	Copper (Cu)	7440-50-8	0.15151	99.99	0.17708
			Subtotal	0.15153	100	0.1771
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02612	0.05	0.03053
	Copper alloy	Zinc (Zn)	7440-66-6	0.05223	0.1	0.06105
	Copper alloy	Iron (Fe)	7439-89-6	1.20136	2.3	1.40415
	Copper alloy	Copper (Cu)	7440-50-8	50.95331	97.55	59.55427
			Subtotal	52.23302	100	61.05
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.48768	100.0	0.57
			Subtotal	0.48768	100	0.57
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.69212	1.5	0.80895
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.38342	9.5	5.12335
	Filler	Silica fused	60676-86-0	40.60435	88.0	47.4584
	Carbon Black	Carbon black	1333-86-4	0.46141	1.0	0.5393
			Subtotal	46.1413	100	53.93
Die Attach		Aromatic Polyester Resin	60088-52-0	0.00327	2.5	0.00383
		Paraffin wax	8002-74-2	0.00916	7.0	0.01071
		Epoxy resin system		0.02618	20.0	0.0306
		Silver (Ag)	7440-22-4	0.09229	70.5	0.10787
			Subtotal	0.1309	100	0.15301
			Total	100.00001	100	116.88011

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